

# ROHM RB-D610Q339TB64 Development Support System User Manual

Home » ROHM » ROHM RB-D610Q339TB64 Development Support System User Manual





#### **Dear customer**

ROHM Co., Ltd. ("ROHM"), on the 1st day of April, 2024, has absorbed into merger with 100%-owned subsidiary of LAPIS Technology Co., Ltd.

Therefore, all references to "LAPIS Technology Co., Ltd.", "LAPIS Technology" and/or "LAPIS" in this document shall be replaced with "ROHM Co., Ltd."

Furthermore, there are no changes to the documents relating to our products other than the company name, the company trademark, logo, etc.

Thank you for your understanding.

#### **Notes**

- 1. The information contained herein is subject to change without notice.
- 2. When using LAPIS Technology Products, refer to the latest product information (data sheets, user's manuals, application notes, etc.), and ensure that usage conditions (absolute maximum ratings, recommended operating

conditions, etc.) are within the ranges specified. LAPIS Technology disclaims any and all liability for any malfunctions, failure or accident arising out of or in connection with the use of LAPIS Technology Products outside of such usage conditions specified ranges, or without observing precautions. Even if it is used within such usage conditions specified ranges, semiconductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury, fire or the other damage from break donor malfunction of LAPIS Technology Products, please take safety at your own risk measures such as complying with the aerating characteristics, implementing redundant and fire prevention designs, and utilising backups and fail safe procedures. You are responsible for evaluating the safety of the final products or systems manufactured by you.

- 3. Descriptions of circuits, software and other related information in this document are provided only to illustrate the standard operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. And the peripheral conditions must be taken into account when designing circuits for mass production. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, and other related information.
- 4. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of LAPIS Technology or any third party with respect to LAPIS Technology Products or the information contained in this document (including but not limited to, the Product data, drawings, charts, programs, algorithms, and application examples etc.). Therefore LAPIS Technology shall have no responsibility whatsoever for any dispute, concerning such rights owned by third parties, arising out of the use of such technical information.
- 5. The Products are intended for use in general electronic equipment (AV/OA devices, communication, consumer systems,gaming/entertainment sets, etc.) as well as the applications indicated in this document. For use of our Products in applications requiring a high degree of reliability (as exemplified below), please be sure to contact a LAPIS Technology representative and must obtain written agreement: transportation equipment (cars, ships, trains, etc.), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems,etc. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising by using the Product for purposes not intended by us. Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters, etc.
- 6. The Products specified in this document are not designed to be radiation tolerant.
- 7. LAPIS Technology has used reasonable care to ensure the accuracy of the information contained in this document. However, LAPIS Technology does not warrant that such information is error-free and LAPIS Technology shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
- 8. Please use the Products in accordance with any applicable environmental laws and regulations, such as the RoHS Directive. LAPIS Technology shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
- 9. When providing our Products and technologies contained in this document to other countries, you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act.
- 10. Please contact a ROHM sales office if you have any questions regarding the information contained in this document or LAPIS Technology's Products.
- 11. This document, in part or in whole, may not be reprinted or reproduced without prior consent of LAPIS Technology

(Note) "LAPIS Technology" as used in this document means LAPIS Technology Co., Ltd.

#### **Contents**

- 1 Overview
- 2 Operational notes
- 3 Hardware specifications
- **4 Board Outline Diagram**
- 5 Specification
  - **5.1 Power Circuit**
  - 5.2 LED(P22-P24)
  - 5.3 ADC(AIN4-AIN7)
  - 5.4 Jack
  - 5.5 CN1 Connector
  - 5.6 PCB specification, BOM list and
  - **Schematic**
  - 5.7 BOM list
  - 5.8 Schematic
  - 5.9 Revision History
- 6 Documents / Resources
  - **6.1 References**
- 7 Related Posts

#### Overview

This instruction manual is for the RB-D610Q339TB64 which is the reference board for ML610Q339 (hereinafter referred to as "MCU") that is 8-bit micro controller with voice output function.

This board can be combined with on-chip debug tool EASE1000 V2 and software development environment (DUT8 and MWU16) to do the following:

- Development and debugging of the MCU control software.
- Programming control and sound code data to the MCU internal Flash-ROM.
- · Voice playback by the MCU.

#### **Operational notes**

The following describes the precautions to follow when handling the RB-D610Q339TB64.

- Turn off the power when inserting and removing jumper socket from PWR/VREF /SPVDD Jumper pin on the RBD610Q339TB64.
- Turn off the power when attaching and reattaching external board, device and cable from CN 1/CN 2/CNE Connector on the RB-D610Q339TB64.
- Connect only monaural speakers to the jack on the RB-D610Q339TB64.
- RB-D610Q339TB64 is a device used only by experts in R&D facilities for research and development purposes.
   RBD610Q339TB64 is not intended to be used in mass-produced products or parts thereof.
- The information in this document is subject to change without notice due to product improvement and technological improvement. Prior to use, please ensure that the information is up to date.
- LAPIS Technology does not provide any RB-D610Q339TB64 support. Replace only in case of initial failure.

# **Hardware specifications**

Table 1 shows the hardware specifications of RB-D610Q339TB64. For more information about the connection of the mounted components, see the schematic.

## **Table 1 Hardware specifications**

Mounted LSI	• <b>U1</b> : ML610Q339 64pin TQFP
	PWR(J1): Jumper for selecting the power supply input (3pin pin-heade r and short pin)
	VREF(J2): Jumper for selecting VREF(3pin pin-header and short pin)
	SPVDD(J3): Jumper for selecting SPVDD(3pin pin-header and short p in)
	C1-C4: Capacitors for Powers
Other Mounted components	• <b>P22-P24</b> : LEDs
	R1-R3: Resistors for LEDs
	R4-R6: Jumper Chip for connecting LEDs
	R7-R10: Resistors for Successive Approximation Type A-D Converter
	JACK: Jack for connecting Speakers
	CNE: Connector for EASE1000 V2(14pin connector)
	C5-C8: Capacitors for Successive Approximation Type A-D Converter
Pads (or/and) Through holes for mo	

unting components	• CN1-CN2: Connectors for user application system (32pin, 2.54mm pitc h, φ0.8mm)
	SP1: Land for fer rite beads(1608)
Power check pins/pads	VDD SPVDD UVDD USPVDD VSS SPVSS AIN4-AIN7 (φ0.8mm)
Operating voltage	• +2.0 +5.5V
Board size	• 55.88 mm x 93.98 mm

# **Board Outline Diagram**

Figure 1 shows an outline diagram of the RB-D610Q339TB64.

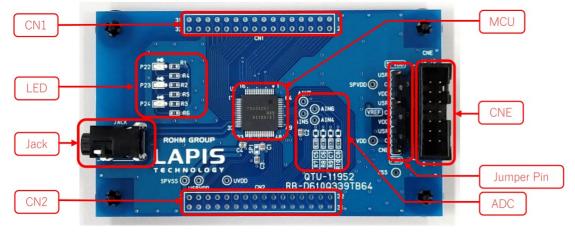


Figure 1 Board Outline Diagram

## **Specification**

#### **Power Circuit**

Figure 2 shows a power circuit of the RB-D610Q339TB64. The RB-D610Q339TB64 has jumper pins that can switch the supply source of the VDD / VREF / SPVDD pins of MCU. Each is explained below.

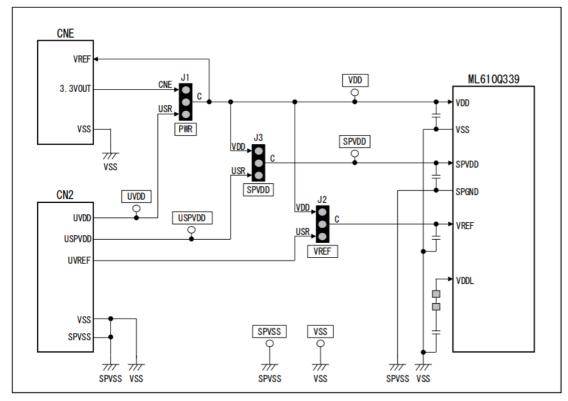


Figure 2 Power circuit

#### PWR jumper pin(J1)

PWR jumper pin can switch the supply source of VDD pin of MCU."

PWR	Contents
CNE	VDD pin is connected to 13pin of CNE.
USR	VDD pin is connected to 9 pin (UVDD) of CN2.

When attaching "EASE1000 V2" on the board, PWR jumper pin set to "EASE" if power supply from 13pin of CNE connector.

PWR jumper pin set to "USR" if power supply from CN1 connector.

#### VREF jumper pin(J2)

VREF jumper pin can switch the supply source of VREF pin of MCU.

VREF	Contents
VDD	VREF pin is connected to 2pin of PWR jumper pin.
USR	VREF pin is connected to 19pin (UVREF) of CN2.

VREF jumper pin set to "VDD" if power supply from VDD as same as selecting PWR jumper pin. VREF jumper pin set to "USR" if power supply from CN2 connector.

#### SPVDD jumper pin(J3)

SPVDD jumper pin can switch the supply source of SPVDD pin of MCU.

SPVDD	Contents
VDD	SPVDD pin is connected to 2pin of PWR jumper pin.
USR	SPVDD pin is connected to 3/4pins (USPVDD) of CN2.

SPVDD jumper pin set to "VDD" if power supply from VDD as same as selecting PWR jumper pin. SPVDD jumper pin set to "USR" if power supply from CN1 connector.

#### LED(P22-P24)

P22-24 pins of MCU on the RB-D610Q339TB64 allow direct LEDs drive. Enable to use LEDs connecting these pins when the N-channel open drain output is selected. Unmounted register on the board indicated by "R4-R6" when not using LEDs. Figure 3 shows the LED circuit processing example.

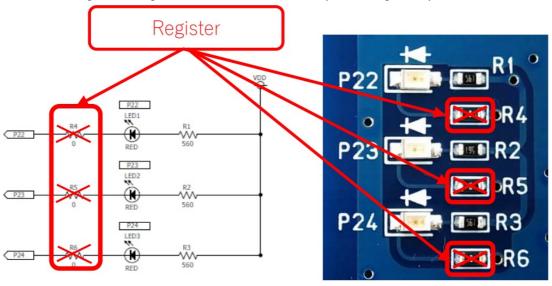


Figure 3 LED circuit processing example

#### ADC(AIN4-AIN7)

The RB-D610Q339TB64 has registers indicated by "R7-R10" and capacitors indicated by "C5-C8" (not mounted) so that P44-P47 pins of MCU are enable to use as AIN4-AIN7 which are Successive Approximation type A-D Converter functions. Mount a noise reduciton capacitor on board land indicated by "C5-C8" if necessary. Figure 4 shows the ADC circuit processing example. When using the Succesive Approximation type A-D Converter functions without using resistors, apply a voltage to the through hole.

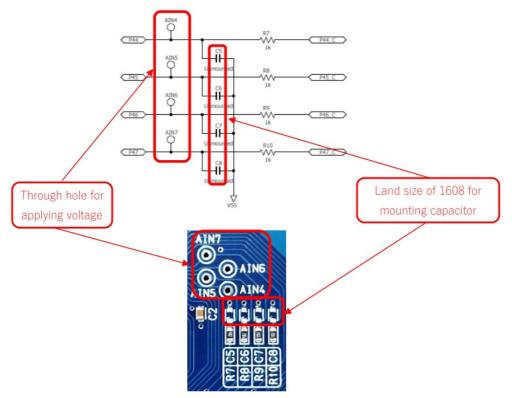


Figure 4 ADC circuit processing example

#### **Jack**

Jack is connected to SPP/SPM pins of the MCU. Connect only monaural speakers to the jack.

#### **CN1 Connector**

The through holes indicated by "CN1" are enable to mount connector that specification is double row, 16 positions and 2.54mm(0.1mil) pich.

Table 2 shows a CN1 connector pin assignment.

Table 2 CN1 connector pin assignment

CN1	Connected to			Domonica
Pin number	Part Symbol	Number	Pin name	- Remarks
1	U1	1	P93	
2	U1	2	P94	
3	U1	3	P80/EXI0	
4	U1	4	P81/EXI1	
5	U1	5	P20/LED0	
6	U1	6	P21/LED1	
7	U1	7	P22/LED2	
8	VSS	_	VSS	
9	U1	9	P23/LED3	

10	U1	10	P24/LED4	
11	U1	11	P25/LED5	
12	U1	12	P91	
13	U1	13	P95	
14	U1	14	P96	
15	VSS	-	VSS	
16	VSS	-	VSS	
17	U1	17	PA7	
18	U1	18	PA6	
19	U1	19	PA5	
20	U1	20	PA4	
21	U1	21	P82/EXI2	
22	U1	22	P83/EXI3	
23	U1	23	PA3	
24	U1	24	PA2	
25	U1	25	PA1	
26	U1	26	PA0	
27	U1	27	P90	
28	U1	28	RESET_N	
29	U1	29	SPP	
30	U1	30	SPP	
31	U1	31	SPM	
32	U1	32	SPM	

#### **CN2 Connector**

The through holes indicated by "CN2" are enable to mount connector that specification is double row, 16 positions and 2.54mm(0.1mil) pich.

Table 3 shows a CN2 connector pin assignment.

Table 3 CN2 connector pin assignment

CN2		Connected to		
Pin number	Part Symbol	Number	Pin name	Remarks
1	U1	33	SPVSS	
2	U1	34	SPVSS	
3	J3	3	USPVDD	J3:SPVDD jumper

4	J3	3	USPVDD	J3:SPVDD jumper
5	U1	37	P84/EXI4	
6	U1	38	P92	
7	VSS	-	VSS	
8	VSS	_	VSS	
9	J1	3	UVDD	J1:PWR jumper
10	U1	42	PB0	
11	U1	43	PB1/TIA0A	
12	U1	44	PB2/TIA0C	
13	U1	45	PB3	
14	U1	46	PB4	
15	U1	47	PB5	
16	U1	48	PB6	
17	U1	49	PC3	
18	U1	50	PC2	
19	J2	3	UVREF	J2:VREF jumper
20	U1	52	P40/AIN0/HPC0	
21	U1	53	P41/AIN1/HPC1	
22	U1	54	P42/AIN2/TIAOUT	
23	U1	55	P43/AIN3	
24	U1	56	P44/AIN4	
25	U1	57	P45/AIN5	
26	U1	58	P46/AIN6	
27	U1	59	P47/AIN7	
28	U1	60	P85/EXI5	
29	U1	61	P86/EXI6	
30	U1	62	P87/EXI7	
31	U1	63	PC0	
32	U1	64	PC1	

#### **CNE** connector

CNE connector is used to connect the on-chip debug tool EASE1000 V2 manufactured by LAPIS Technology o.,Ltd.

Refer to the "EASE1000 V2 User's Manual" for details.

# PCB specification, BOM list and Schematic

# PCB specification

Figure 5 shows the PCB dimensional outline diagram and layout of components

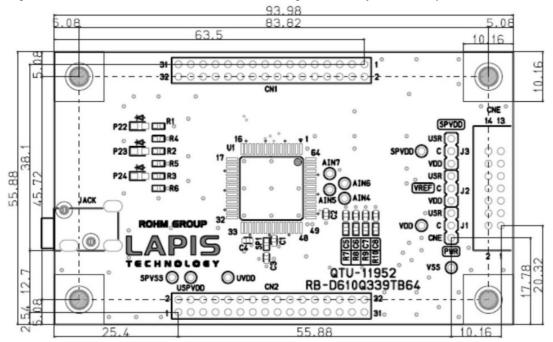


Figure 5 PCB dimensional outline diagram and layout of components (Top view)

# **BOM list**

**Table 4 BOM list** 

	Parts Number	Symbol	Contents	Qty.	Vendor
1	QTU-11952	RB-D610Q339TB64	PWB	1	LAPIS Technology Co. , Ltd.
2	C1608X7R1E105K08 0AB	C1,C2,C3,C4	Ceramic Capacitor 1uF/25V X7R	4	TDK
3	_	C5,C6,C7,C8	Unmounted	4	_
4	-	CN1,CN2	Unmounted	2	_
5	HIF3FC-14PA-2.54D SA	CNE	14pin Header	1	HIROSE
6	MJ-354A0	JACK	Monaural Speaker Jack	1	MARUSHIN
7	SML-M13UT	LED1,LED2,LED3	LED Red	3	ROHM
8	MCR03EZPJ561	R1,R2,R3	Resistor 560Ω ±5%	3	ROHM
9	MCR03EZRJ000	R4,R5,R6	Resistor 0Ω	3	ROHM
10	MCR03EZPJ102	R7,R8,R9,R10	Resistor 1kΩ ±5%	4	ROHM
11	A2-3PA-2.54DSA(71)	J1,J2,J3	3pin Header	3	HIROSE
12	HIF-3GA-2.54SP	_	Jumper Socket	3	HIROSE
13	_	TP1,TP2,TP3,TP4,TP5 ,TP6	Unmounted	6	-
14	_	AIN4, AIN5, AIN6, AIN 7	Unmounted	4	-
15	ML610Q339-NNNTB	U1	MCU	1	LAPIS Technology Co. , Ltd.
16	FF013-P3555-AR791	_	Rubber leg, Push rivet	4	KOYO FASTENER

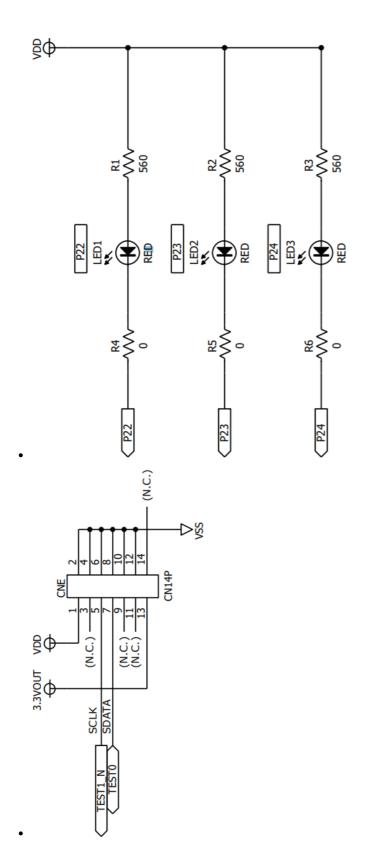
## Note]

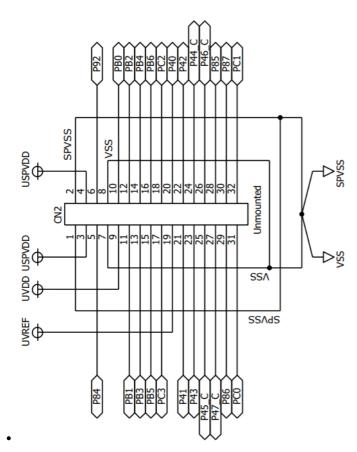
- The diameter of through hole of CN1 and CN2 is 0.8mm.

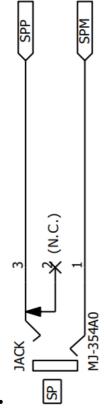
  Using CN1 and CN2, the diameter of connector pin should use the connector below 0.8mm, such as 0.5mm.
- The parts may be changed into another parts with equivalent part special quality.

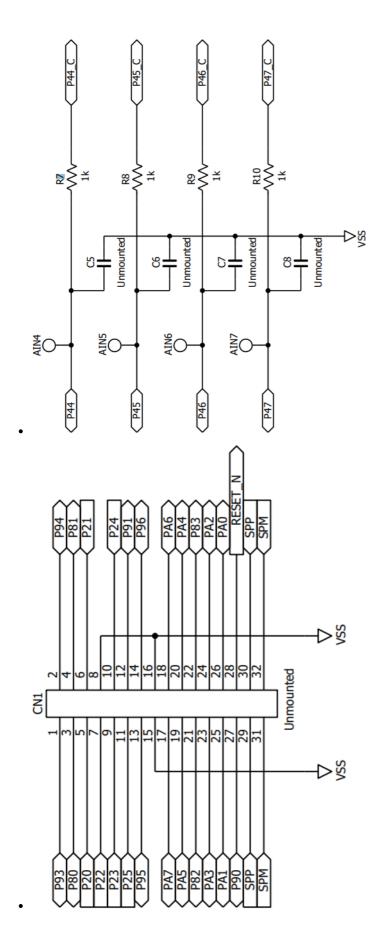
## **Schematic**

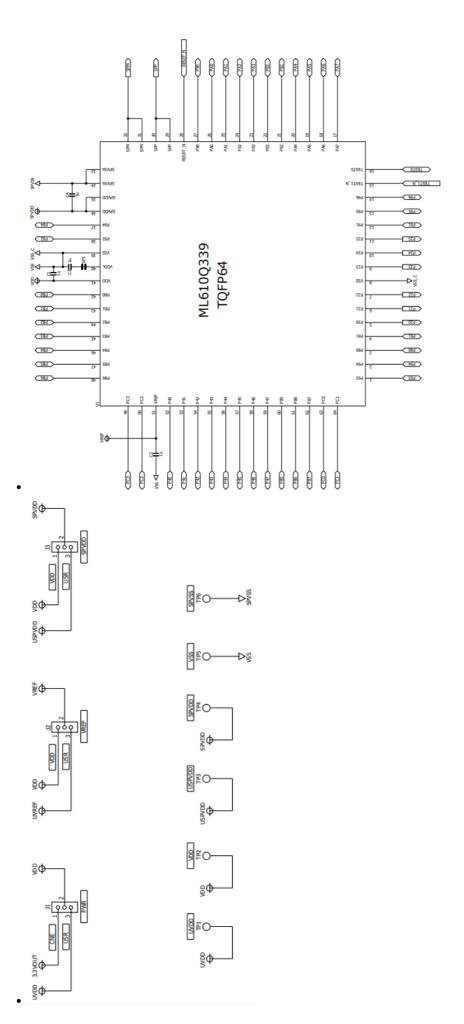
The schematic of RB-D610Q339TB64 is shown below.











LAPIS Technology Co., Ltd.	
RB-D610Q339TB64	
APPLICATION ML610Q339 TQFP64 Reference Board	
DWG No. QTS-11822	
SHEET 1 of 1	Rev. 1.0

## **Revision History**

Document No.	Issu e D	Page		Description
Document No.	ate	Previous Edition	New Edition	Description
FJBL610Q339RB-01	Jan 13, 202 2	_	_	First edition.



#### **Documents / Resources**



ROHM RB-D610Q339TB64 Development Support System [pdf] User Manual RB-D610Q339TB64 Development Support System, RB-D610Q339TB64, Development Support System, Support System

## References

- Notice of Site Integration | LAPIS Technology
- User Manual

#### Manuals+, Privacy Policy

This website is an independent publication and is neither affiliated with nor endorsed by any of the trademark owners. The "Bluetooth®" word mark and logos are registered trademarks owned by Bluetooth SIG, Inc. The "Wi-Fi®" word mark and logos are registered trademarks owned by the Wi-Fi Alliance. Any use of these marks on this website does not imply any affiliation with or endorsement.